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REQUEST FOR RECONSIDERATION

Notwithstanding Applicant's arguments filed 6 January 2006, the Examiner has maintained his rejection of the claims. Specifically, the Examiner states as follows:

"Applicant argues prior art does not disclose treating the ceramic surface with palladium in preparation for soldering. However, Applicant does not claim preparing a ceramic surface for soldering with a non-magnetic material. Applicant also argues prior art does not solve the problems recognized by the Applicants. However subjective intent does not further limit the scope of the claims". With that, the Examiner made the rejection final.

In response, Applicant respectfully requests the Examiner to reconsider his position because: (1) there is no disclosure in the combination of Peterson and Ouellet to overlay palladium on a tungsten-treated "interface portion" of the housing as set forth in the claims; and (2) there is no disclosure of providing a solderable interface consisting essentially of a tungsten layer, a palladium layer and a protective coating as recited in Claim 8.

There is no disclosure in the combination of Peterson and Ouellet of overlaying palladium on a tungsten-treated interface portion. As set forth in the specification, "the term 'interface portion' refers to the portion of the housing which is joined to another component of the package, such as a lid." ¶0022. Thus, in the claimed process, the palladium layer is deposited on the portion of the housing which is joined with another component of the package, such as a lid as recited in claim 9. Contrary to the Examiner's position, Ouellet does not disclose overlaying a tungsten-treated interface portion with palladium. Rather, Ouellet is directed to a different type of packaging system in which a microstructure is sealed in a cavity using a deposited capping layer. In other words, the deposited capping layer in Ouellet *is* the cap. It cannot therefore be applied to any "interface portion" of the housing. Indeed, there are no interface portions in Ouellet's housing. *To the contrary*, as discussed in the previous office action, Ouellet criticizes, in general, the technique of soldering a top layer or cover to a substrate. Therefore, Applicants respectfully submit that the

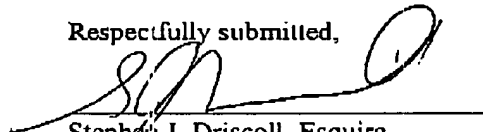
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combination of Peterson and Ouellet fails to disclose overlaying palladium on a tungsten-treated interface portion of the housing. Accordingly, the rejection should be withdrawn and the claims allowed.

The combination of Peterson and Ouellet also fails to disclose a solderable interface consisting essentially of a tungsten layer, a palladium layer, and a protective coating as recited in Claim 8. This element is not disclosed or suggested in the combination of Peterson and Ouellet. Although the Examiner states that "Peterson et al discloses a solderable interface . . . at the interface portion, the solderable interface consisting essentially of the tungsten layer, the palladium layer, and the protective coating (col. 30, line 42 through col. 31, line 9)," the passage to which the Examiner cites simply does not disclose this. Rather, it discloses the sequence of fabricating the package. There is, however, no mention of overlaying a tungsten-treated interface portion with palladium. Indeed, the word "palladium" is not even used in this passage.

Therefore, for the reasons mentioned above, Applicants submit that the rejection should be withdrawn and the claims allowed.

Respectfully submitted,



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